

## 14 + 1 channel buffers for TFT-LCD panels

Datasheet -production data

#### **Features**

■ Wide supply voltage: 5.5 V to 16.8 V

■ Low operating current: 6 mA typical at 25 °C

■ Gain bandwidth product: 1 MHz

■ High current COM amplifier: ±100 mA output current

■ Industrial temperature range: -40 °C to +85 °C

Small package: TQFP48Automotive qualification

### **Application**

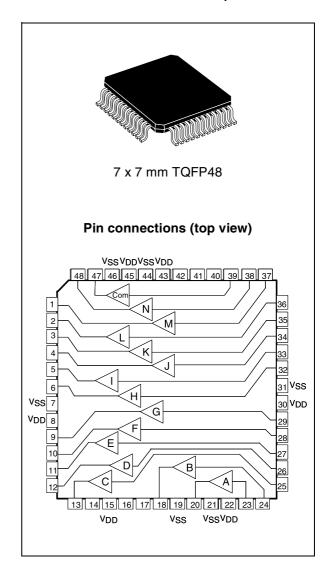
■ TFT liquid crystal display (LCD)

### Description

The TSL1014 device is composed of 14 + 1 channel buffers which are used to buffer the reference voltage for gamma correction in thin film transistor (TFT) liquid crystal displays (LCD).

One "COM" amplifier is able to deliver high output current value, up to ±100 mA. Amplifiers A and B feature positive single supply inputs for common mode voltage behavior. The amplifiers C to N inclusive, and the COM amplifier, feature negative single supply inputs and are dedicated to the highest and lowest gamma voltages.

The TSL1014 device is fully characterized and guaranteed over a wide industrial temperature range (-40 to +85 °C).



### 1 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply voltage (V <sub>DD</sub> - V <sub>SS</sub> )	18	V
V <sub>IN</sub>	Input voltage	V <sub>SS</sub> -0.5 V to V <sub>DD</sub> +0.5 V	٧
l <sub>OUT</sub>	Output current (A to N buffers) Output current (COM buffer)	30 100	mA
I <sub>SC</sub>	Short-circuit current (A to N buffers) Short-circuit current (COM buffer)	±120 ±300	mA
P <sub>D</sub>	Power dissipation <sup>(1)</sup> for TQFP48	1470	mW
R <sub>THJA</sub>	Thermal resistance junction-to-ambient for TQFP48	85	°C/W
T <sub>LEAD</sub>	Lead temperature (soldering 10 seconds)	260	°C
T <sub>STG</sub>	Storage temperature	-65 to +150	°C
TJ	Junction temperature	150	°C
	Human body model (HBM) <sup>(2)</sup>	2000	
ESD	Machine model (MM) <sup>(3)</sup>	200	V
	Charged device model (CDM) <sup>(4)</sup>	1500	

- 1.  $P_D$  is calculated with  $T_{amb}$  = 25 °C,  $T_J$  = 150 °C and  $R_{THJA}$  = 85 °C/W for the TQFP48 package.
- 2. Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5 kW resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.
- 3. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 W). This is done for all couples of connected pin combinations while the other pins are floating.
- Charged device model: all pins and package are charged together to the specified voltage and then discharged directly to ground through only one pin.

Table 2. Operating conditions

	-			
Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Supply voltage (V <sub>DD</sub> - V <sub>SS</sub> )	5.5 to 16.8	V	
T <sub>amb</sub>	Ambient temperature	-40 to +85	°C	
V <sub>IN</sub>	Input voltage (buffers A and B)	$V_{SS}$ +1.5 V to $V_{DD}$	\ <u>\</u>	
	Input voltage (buffers C to N + COM)	V <sub>SS</sub> to V <sub>DD</sub> -1.5 V	V	

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## 2 Typical application schematics

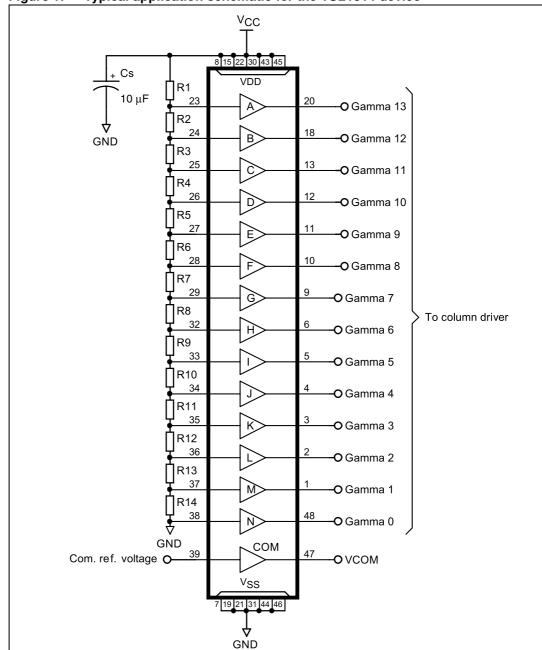


Figure 1. Typical application schematic for the TSL1014 device

#### Note that:

- Amplifiers A and B have their input voltage in the range V<sub>SS</sub> +1.5 V to V<sub>DD</sub>. This is why
  they must be used for high level gamma correction voltages.
- Amplifiers C to N have their input voltage in the range V<sub>SS</sub> to V<sub>DD</sub> 1.5 V. This is why
  they must be used for medium-to-low level gamma correction voltages.
- $\bullet$   $\;$  Amplifier COM has its input voltage range from  $V_{SS}$  to  $V_{DD}$  1.5 V.

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## 3 Electrical characteristics

Table 3. Electrical characteristics for TSL1014IF/TSL1014IFT  $T_{amb}$  = 25 °C,  $V_{DD}$  = +5 V,  $V_{SS}$  = -5 V,  $R_L$  = 10 k $\Omega$ ,  $C_L$  = 10 pF (unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
V <sub>IO</sub>	Input offset voltage	V <sub>ICM</sub> = 0 V			12	mV	
ΔV <sub>IO</sub>	Input offset voltage drift	T <sub>Min</sub> < T <sub>amb</sub> < T <sub>Max</sub>		5		μV/°C	
I <sub>IB</sub>	Input bias current	V <sub>ICM</sub> = 0 V, buffers A and B V <sub>ICM</sub> = 0 V, buffers C to N and COM			140 70	nA	
R <sub>IN</sub>	Input impedance			1		GΩ	
C <sub>IN</sub>	Input capacitance			1.35		pF	
V <sub>OL</sub>	Output voltage low	I <sub>OUT</sub> = -5 mA Buffers C to L Buffers M, N and COM		-4.85 -4.92	-4.80 -4.85	V	
V <sub>OH</sub>	Output voltage high	I <sub>OUT</sub> = 5 mA for positive single supply buffers (A and B)	4.82	4.87		V	
	Output ourrant	(A to N buffers)		±30		mA	
l <sub>OUT</sub>	Output current	COM buffer		±100		IIIA	
PSRR	Power supply rejection ratio	V <sub>CC</sub> = 6.5 to 15.5 V	80	100		dB	
I <sub>CC</sub>	Supply current	No load		6	8.4	mA	
SR	Slew rate (rising and falling edge)	-4 V < V <sub>OUT</sub> < +4 V 20% to 80%		1		V/μs	
t <sub>s</sub>	Settling time	Settling to 0.1%, V <sub>OUT</sub> = 2 V step		5		μs	
BW	Bandwidth at -3 dB	R <sub>L</sub> =10 kΩ, C <sub>L</sub> =10 pF		2		MHz	
G <sub>m</sub>	Phase margin	R <sub>L</sub> =10 kΩ, C <sub>L</sub> =10 pF		60		Degrees	
C <sub>s</sub>	Channel separation	f=1 MHz		75		dB	

Note: Limits are 100% production tested at 25 °C. Behavior at the temperature range limits is guaranteed through correlation and by design.

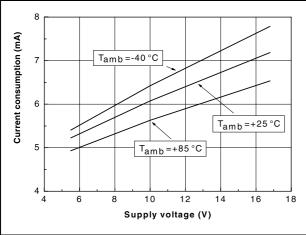
Table 4. Electrical characteristics for TSL1014IYFT (automotive grade)  $T_{amb} = 25~^{\circ}\text{C}, \ V_{DD} = +5~\text{V}, \ V_{SS} = -5~\text{V}, \ R_L = 10~\text{k}\Omega, \ C_L = 10~\text{pF}$  (unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
V <sub>IO</sub>	Input offset voltage	$V_{ICM} = 0 V$ $T_{Min} < T_{amb} < T_{Max}$			12	mV	
ΔV <sub>IO</sub>	Input offset voltage drift	$T_{Min} < T_{amb} < T_{Max}$		5		μV/°C	
I <sub>IB</sub>	Input bias current	$V_{ICM}$ = 0 V, buffers A and B $T_{Min}$ < $T_{amb}$ < $T_{Max}$ $V_{ICM}$ = 0 V, buffers C to N and COM $T_{Min}$ < $T_{amb}$ < $T_{Max}$			140 280 70 140	nA	
R <sub>IN</sub>	Input impedance			1		GΩ	
C <sub>IN</sub>	Input capacitance			1.35		pF	
V <sub>OL</sub>	Output voltage low	$I_{OUT}$ = -5 mA Buffers C to L $T_{Min}$ < $T_{amb}$ < $T_{Max}$ Buffers M, N and COM		-4.85 -4.92	-4.80 -4.76	V	
		$T_{Min} < T_{amb} < T_{Max}$			-4.83		
V <sub>OH</sub>	Output voltage high	I <sub>OUT</sub> = 5 mA for positive single-supply buffers (A and B) T <sub>Min</sub> < T <sub>amb</sub> < T <sub>Max</sub>	4.82 4.80	4.87		V	
	Output current	(A to N buffers)		±30		- mA	
l <sub>out</sub>		COM buffer		±100			
PSRR	Power supply rejection ratio	$V_{CC} = 6.5 \text{ to } 15.5 \text{ V}$ $T_{Min} < T_{amb} < T_{Max}$	80	100		dB	
I <sub>CC</sub>	Supply current	No load T <sub>Min</sub> < T <sub>amb</sub> < T <sub>Max</sub>		6	8.4 9	mA	
SR	Slew rate (rising and falling edge)	-4 V < V <sub>OUT</sub> < +4 V 20% to 80%		1		V/μs	
t <sub>s</sub>	Settling time	Settling to 0.1%, V <sub>OUT</sub> = 2 V step		5		μs	
BW	Bandwidth at -3 dB	$R_L$ = 10 kΩ, $C_L$ = 10 pF		2		MHz	
G <sub>m</sub>	Phase margin	$R_L$ = 10 kΩ, $C_L$ = 10 pF		60		Degrees	
C <sub>s</sub>	Channel separation	f = 1 MHz		75		dB	

Note: Limits are 100% production tested at 25 °C. Behavior at the temperature range limits is guaranteed through correlation and by design.

Figure 2. Supply current vs. supply voltage for various temperatures

Figure 3. Output offset voltage (eq.  $V_{IO}$ ) vs. temperature



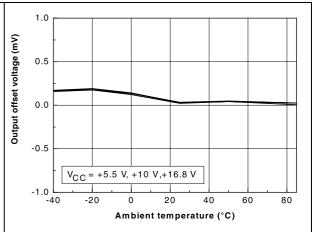
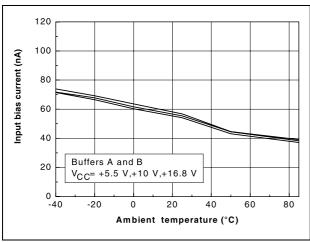


Figure 4. Input current (I<sub>IB</sub>) vs. temperature, buffers A and B

Figure 5. Input current (I<sub>IB</sub>) vs. temperature, buffers C to COM



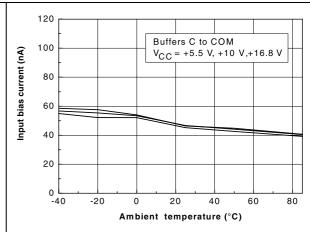
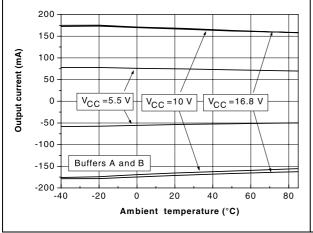


Figure 6. Output current capability vs. temperature, buffers A and B

Figure 7. Output current capability vs. temperature, buffers C to N



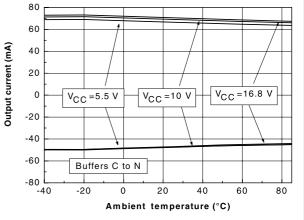


Figure 8. Output current capability vs. temperature, buffer COM

250 200 150 Output current (mA) 100 50  $V_{CC} = \overline{5.5 \text{ V}}$ V<sub>CC</sub> = 10 V, 16.8 V -50 -100 -150 Buffer COM -200 -250 └ -40 -20 20 80 Ambient temperature (°C)

Figure 9. High level voltage drop vs. temperature

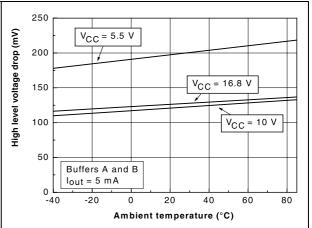


Figure 10. Low level voltage drop vs. temperature, buffers C to L

200 Low level voltage drop (mV)  $V_{CC} = 16.8 \text{ V}$ 150  $V_{CC} = 10 \text{ V}$ 100 50  $V_{CC} = 5.5 V$ Buffers C to L l<sub>out</sub> = 5 mA 0 L -40 -20 20 40 60 80 Ambient temperature (°C)

Figure 11. Low level voltage drop vs. temperature, buffers M, N, and COM

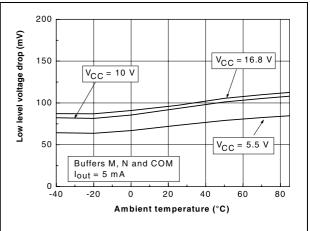
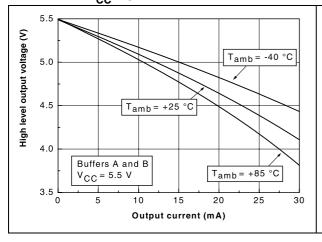


Figure 12. Voltage output high ( $V_{OH}$ ) vs. output current - buffers A and B,  $V_{CC}$  = 5 V

Figure 13. Voltage output high (V<sub>OH</sub>) vs. output current - buffers A and B, V<sub>CC</sub> = 10 V



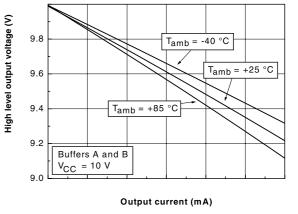
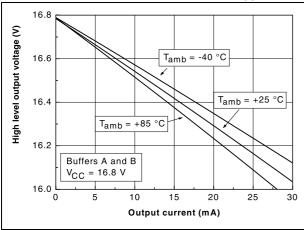


Figure 14. Voltage output high ( $V_{OH}$ ) vs. output Figure 15. Voltage output low ( $V_{OL}$ ) vs. output current - buffers A and B,  $V_{CC}$  = 16.8 V current - buffers C to L,  $V_{CC}$  = 5.5 V



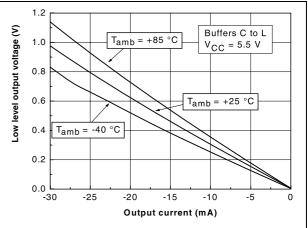
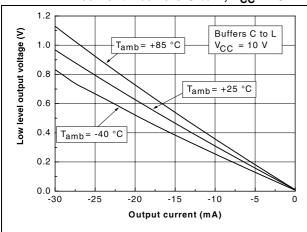


Figure 16. Voltage output low  $(V_{OL})$  vs. output Figure 17. Voltage output low  $(V_{OL})$  vs. output current - buffers C to L,  $V_{CC}$  = 10 V current - buffers C to L,  $V_{CC}$  = 16.8 V



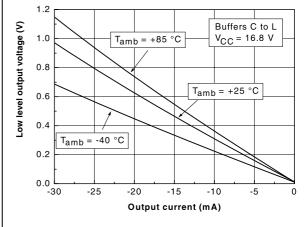


Figure 18. Voltage output low ( $V_{OL}$ ) vs. output current - buffers M, N and COM,  $V_{CC}$  = 5.5 V

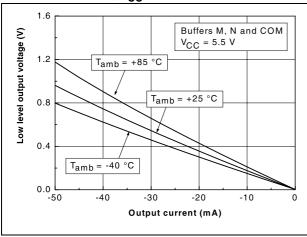


Figure 19. Voltage output low ( $V_{OL}$ ) vs. output current - buffers M, N and COM,  $V_{CC}$  = 10 V

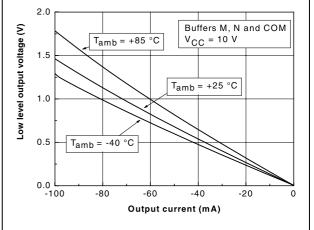


Figure 20. Voltage output low ( $V_{OL}$ ) vs. output current - buffers M, N and COM,  $V_{CC}$  = 16.8 V

Figure 21. Positive slew rate vs. temperature,  $V_{CC} = 5.5 \text{ V}$ 

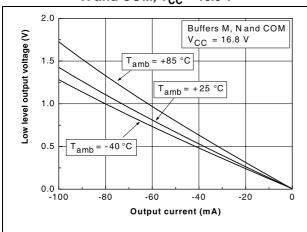
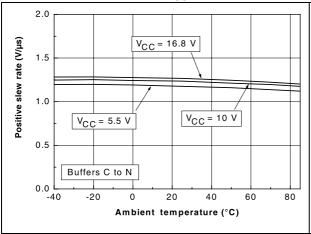


Figure 22. Positive slew rate vs. temperature,  $V_{CC} = 10 \text{ V}$ 

Figure 23. Positive slew rate vs. temperature,  $V_{CC} = 16.8 \text{ V}$ 



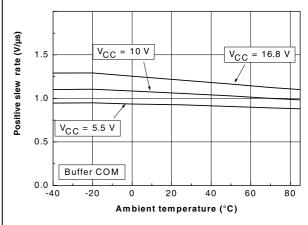
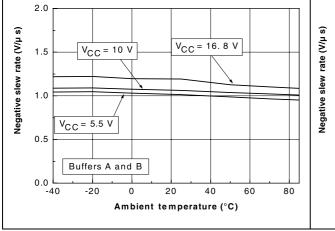


Figure 24. Negative slew rate vs. temperature, buffers A and B

Figure 25. Negative slew rate vs. temperature, buffers C to N



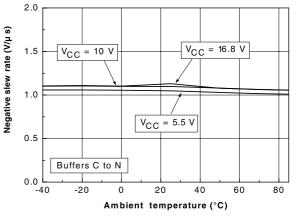


Figure 26. Negative slew rate vs. temperature, buffer COM

2.0 V<sub>CC</sub> = 10 V V<sub>CC</sub> = 16.8 V V<sub>CC</sub> = 16.8 V V<sub>CC</sub> = 5.5 V Buffer COM 0.0 -40 -20 0 20 40 60 80 Ambient temperature (°C)

Figure 27. Large signal response - buffers A and B - positive step

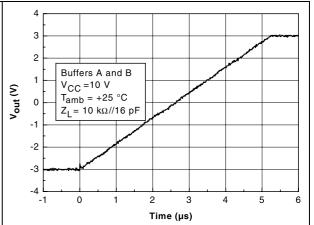


Figure 28. Large signal response - buffers A and B - negative step

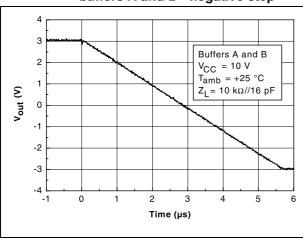


Figure 29. Large signal response - buffers C to N - positive step

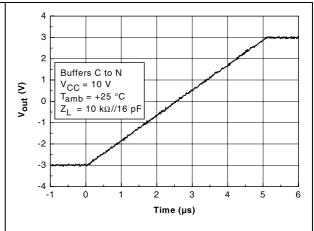


Figure 30. Large signal response - buffers C to N - negative step

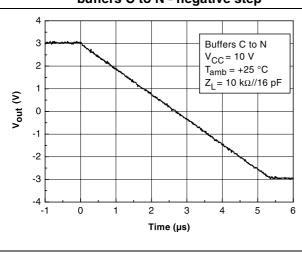
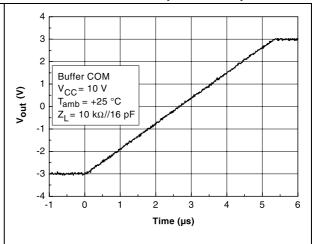


Figure 31. Large signal response - buffer COM - positive step



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Figure 32. Large signal response - buffer COM - negative step

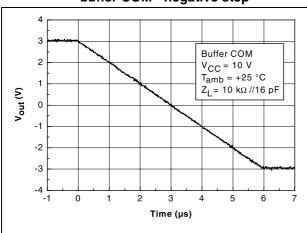


Figure 33. Small signal response - buffers A and B

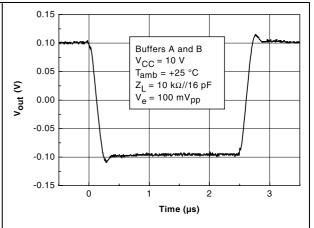


Figure 34. Small signal response - buffers C to N

Figure 35. Small signal response - buffer COM

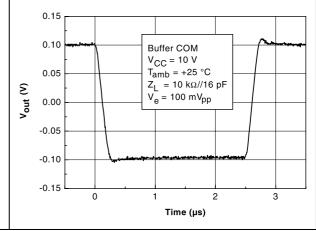


Figure 36. Output voltage response to current transient - buffers A and B,  $\Delta I = 0$  to 30 mA

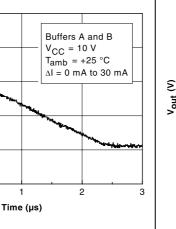
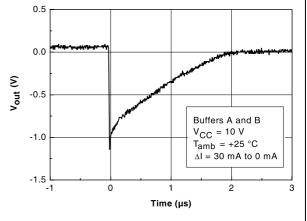


Figure 37. Output voltage response to current transient - buffers A and B,  $\Delta I = 30$  to 0 mA



2.0

1.5

1.0

0.5

0.0

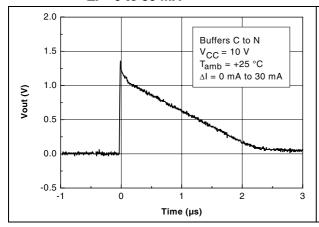
-0.5

0

Vout (V)

Figure 38. Output voltage response to current transient - buffers C to N,  $\Delta I = 0$  to 30 mA

Figure 39. Output voltage response to current transient - buffers C to N,  $\Delta I = 30$  to 0 mA



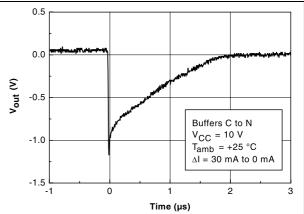
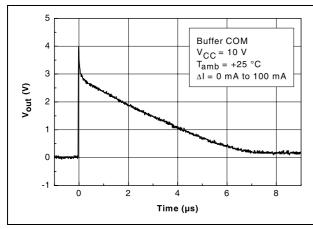


Figure 40. Output voltage response to current transient - buffer COM,  $\Delta I = 0$  to 100 mA

Figure 41. Output voltage response to current transient - buffer COM,  $\Delta I = 100$  to 0 mA



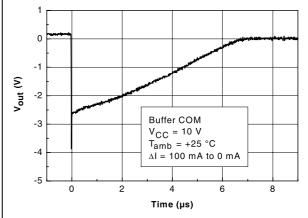
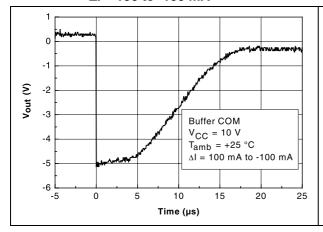
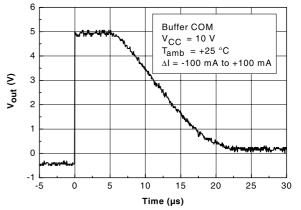


Figure 42. Output voltage response to current transient - buffer COM,  $\Delta I = 100$  to -100 mA

Figure 43. Output voltage response to current transient - buffer COM,  $\Delta I = -100$  to +100 mA





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TSL1014 Package information

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: <a href="www.st.com">www.st.com</a>. ECOPACK is an ST trademark.

Package information TSL1014

A A2

A1

O,08 mm
O10 inch
SEATING PLANE

D1

D3

SET TO PACKAGE PLANE

D1

D3

SET TO PACKAGE

O,25 mm
O10 inch
GAGE PLANE

D1

D3

SET TO PACKAGE

O,10 inch
GAGE PLANE

D1

D1

D3

SET TO PACKAGE

O,10 inch
GAGE PLANE

D1

D1

D2

D1

D3

SET TO PACKAGE

O110596/C

Figure 44. TQFP48 package outline

Table 5. TQFP48 package mechanical data

	Dimensions						
Symbol	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α			1.6			0.063	
A1	0.05		0.15	0.002		0.006	
A2	1.35	1.40	1.45	0.053	0.055	0.057	
В	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.09		0.20	0.0035		0.0079	
D		9.00			0.354		
D1		7.00			0.276		
D3		5.50			0.216		
е		0.50			0.020		
E		9.00			0.354		
E1		7.00			0.276		
E3		5.50			0.216		
L	0.45	0.60	0.75	0.018	0.024	0.030	
L1		1.00			0.039		
K	0°	3.5°	7°	0°	3.5°	7°	

# 5 Ordering information

Table 6. Order codes

Order code	Temperature range	Package	Packing	Marking
TSL1014IF			Tray	SL1014I
TSL1014IFT	-40 °C to +85 °C	TQFP48	Tape and reel	3L10141
TSL1014IYFT <sup>(1)</sup>			Tape and reel	SL1014Y

Qualified and characterized according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 and Q 002 or equivalent.

Revision history TSL1014

# 6 Revision history

Table 7. Document revision history

Date	Revision	Changes
01-Jul-2005	1	Initial release - Product in full production.
01-Sep-2005	2	Lead temperature corrected in <i>Table 1 on page 2</i> .  Electrical characteristics graphs re-ordered from <i>Figure 2 on page 6</i> to <i>Figure 43 on page 12</i> .
07-Mar-2007	3	Notes added on ESD in <i>Table 1 on page 2</i> .  Maximum operating supply voltage increased in <i>Table 2 on page 2</i> .  Input voltage parameters added in <i>Table 2 on page 2</i> .  V <sub>OL</sub> limits changed for Buffers C to L in <i>Table 4 on page 5</i> .
09-Jun-2008	4	Electrical characteristics table added for automotive parts.  Order codes added for automotive parts.
19-Aug-2008	5	Modified I <sub>CC</sub> typical and maximum values for standard parts in <i>Table 3</i> .  Updated all curves ( <i>Figure 2</i> to <i>Figure 43</i> ).  Added ESD charged device model value in <i>Figure 1</i> .
11-May-2009	6	Modified footnote under Table 6: Order codes.
14-Nov-2012	7	Removed TSL1014IYF device from <i>Table 4</i> and <i>Table 6</i> . Renamed titles of <i>Figure 4</i> to <i>Figure 8</i> , <i>Figure 10</i> to <i>Figure 32</i> , and <i>Figure 36</i> to <i>Figure 43</i> (added conditions). Reformatted <i>Section 4</i> (added <i>Figure 44</i> ). Minor corrections throughout document.

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